

IN THE DRAWINGS

Figures 2-9, 19, and 23 have been amended as indicated in red in the attached annotated marked-up drawings. Replacement sheets of Figures 2-9, 19, and 23 are also attached.

REMARKS

The revised restriction requirement is noted. It is not believed that it is material since claim 10 is indicated to be generic and is believed to be patentable. However, it seems to be unfair to change the restriction requirement and make it final. Therefore, if claim 10 is not allowed, reconsideration is respectfully requested.

With respect to the objections to the drawings, in paragraph 3, the changes have been made. In subparagraph (A), the reference character 30 on page 8 of the specification has been changed to 29.

With respect to subparagraph (B), the reference numerals 10 and 40 have been removed from the drawings, the reference numerals 38a and 38b have been changed to 38, and the reference numeral 110 and the reference numeral 150 have been removed.

With respect to the objections set forth in subparagraph (C), claim 13 has been amended to change the order. Claim 20 has been amended to change “condenser” to “re-combiner” and support for re-combiner has been provided in claim 19 by changing “combiner” to “re-combiner.” Claim 21 has been amended to remove the objection.

With respect to paragraph 4 of the office action, the objections set forth in subparagraph (A), (B), and (C) have been made.

The objections set forth in paragraph 6 have, therefore, also been corrected.

Claim 10 was rejected under Kenny. However, Kenny does not teach any kind of re-combiner. The item 1410 pointed to in Kenny is simply a heat sink with fins. A re-combiner is explained at page 10, lines 16-21. It is used to reduce the buildup of gas in the cooling fluid pump by the pump 28. Exposure of the gases to catalytic material 66 results in gas recombination.

Concerning claim 13, it is believed that, as corrected, Kenny does not teach the claimed arrangement.

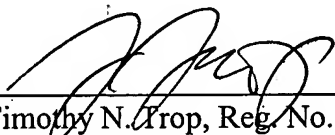
With respect to claim 18, nothing in the cited material seems to support the assertion of a bumpless buildup package. The discussion cited relates to the device 200 which is asserted to be an integrated circuit. It cannot be a package. The package 1300, in Figure 12A, is plainly not a bumpless buildup package. It simply uses a socket, as best as can be determined.

Reconsideration of the rejection of claim 19, on the basis of the absence of both the bumpless buildup layer package and a recombiner in the cited reference, situated as claimed is respectfully requested.

In view of these remarks, the application should now be in condition for allowance.

Respectfully submitted,

Date: May 25, 2005



Timothy N. Trop, Reg. No. 28,994
TROP, PRUNER & HU, P.C.
8554 Katy Freeway, Ste. 100
Houston, TX 77024
713/468-8880 [Phone]
713/468-8883 [Fax]

Applicants for Intel Corporation

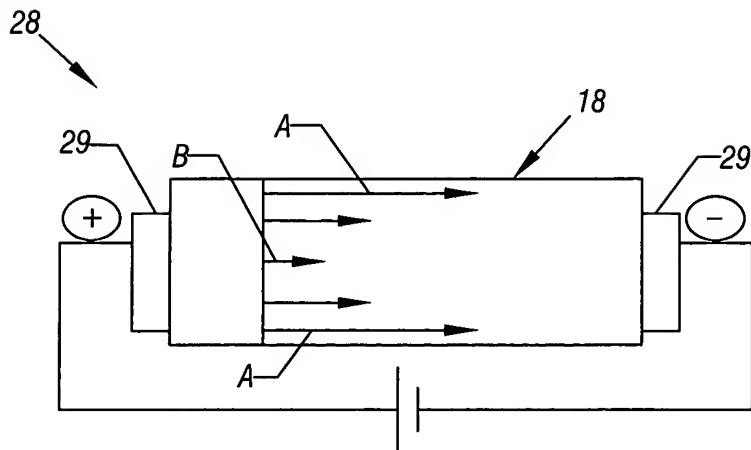


FIG. 1

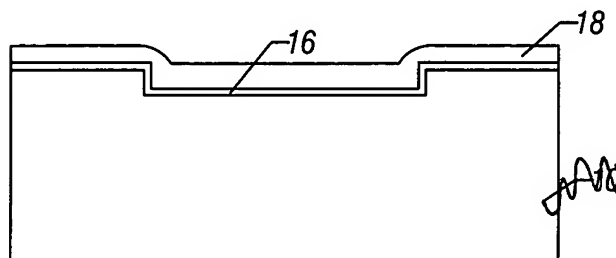


FIG. 2

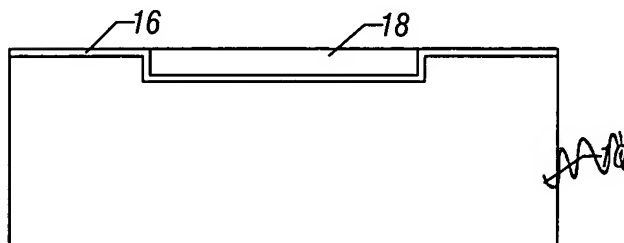


FIG. 3

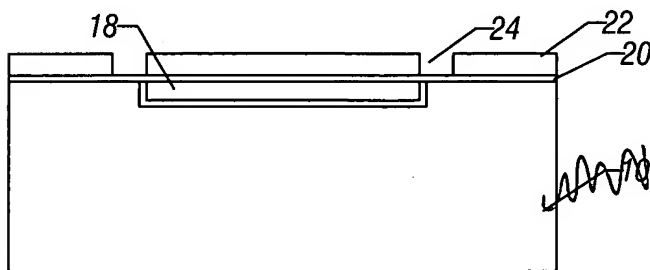


FIG. 4

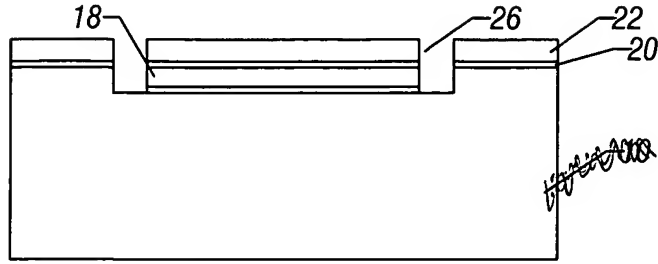


FIG. 5

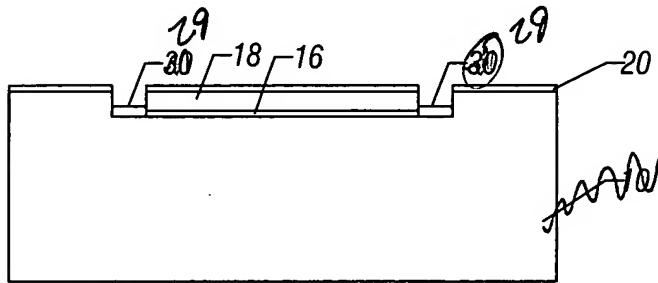


FIG. 6

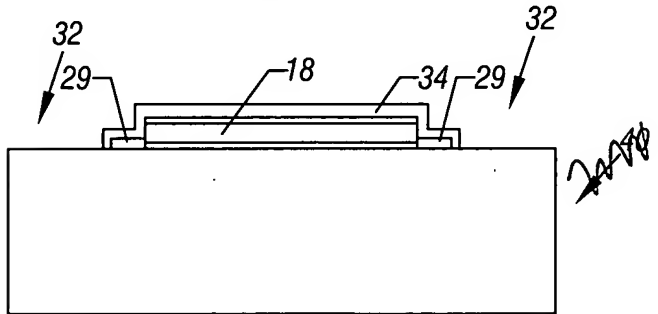


FIG. 7

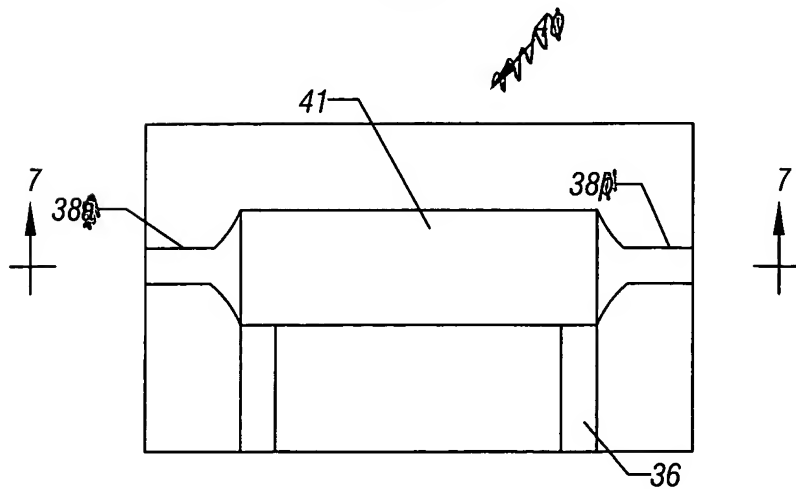


FIG. 8

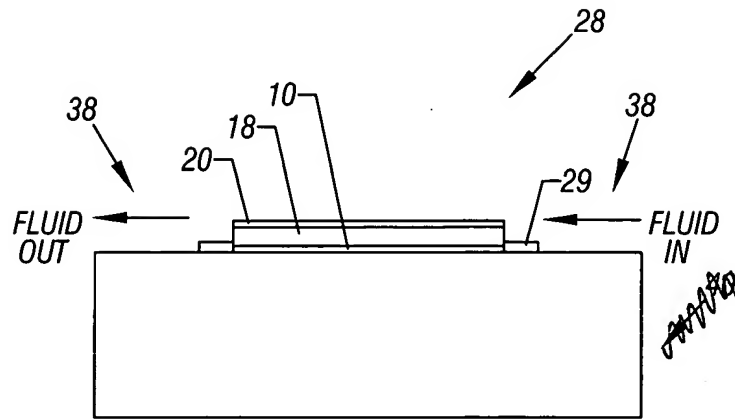


FIG. 9

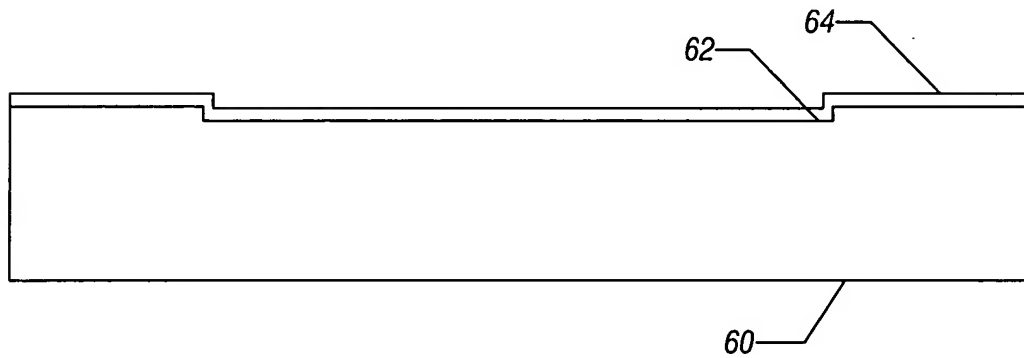


FIG. 10

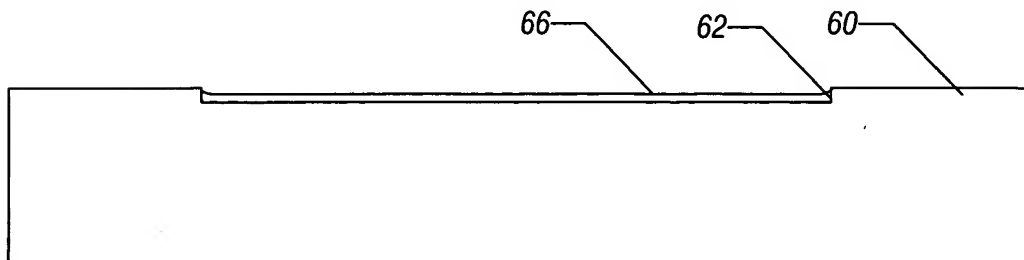


FIG. 11

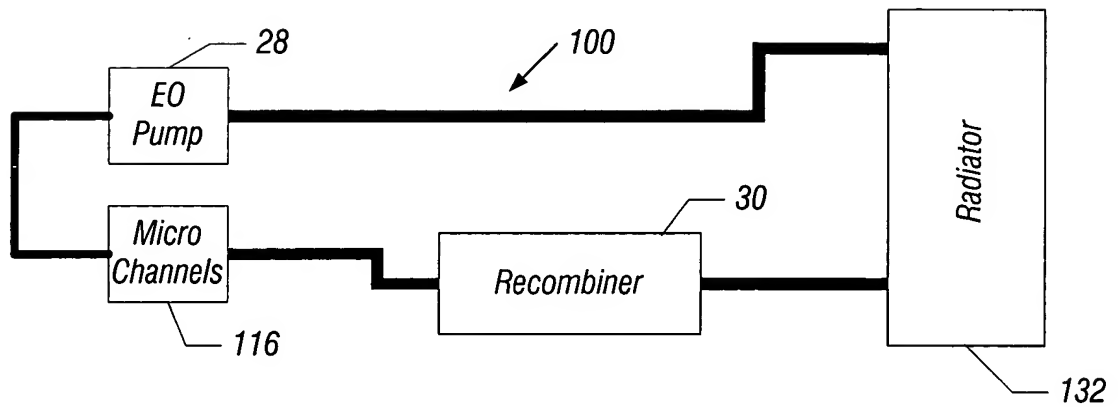


FIG. 18

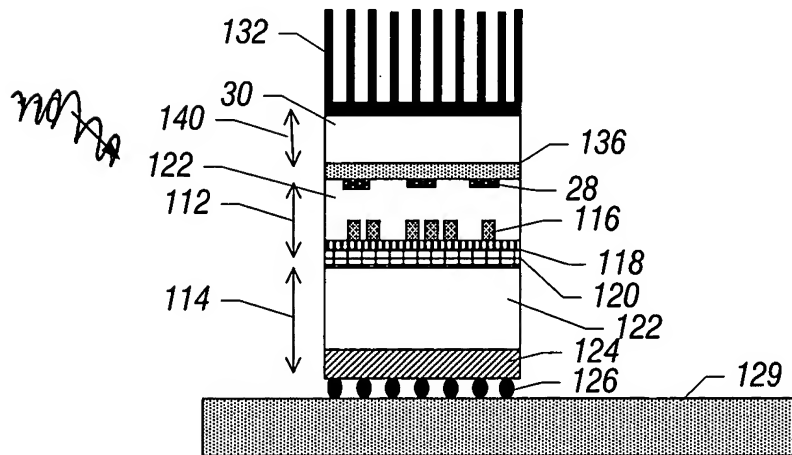


FIG. 19

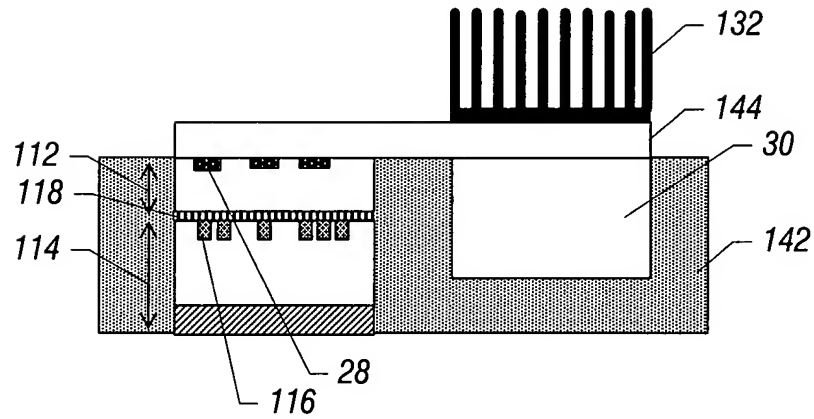


FIG. 22

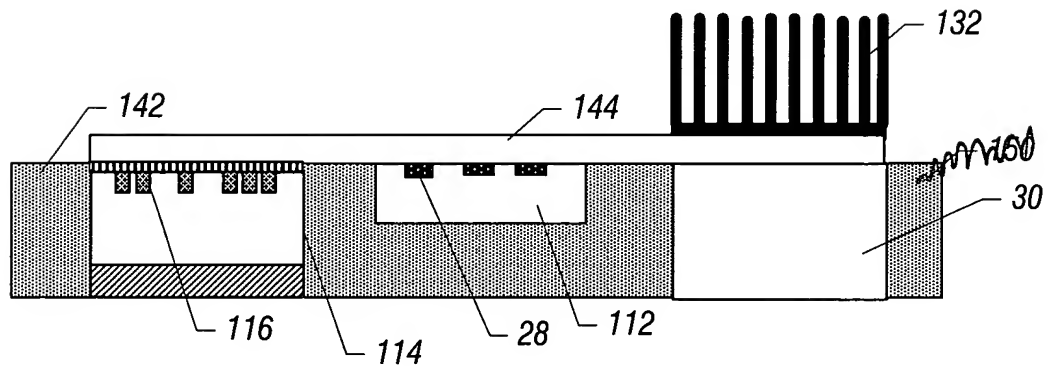


FIG. 23